## 1. Thermal tests

<table>
<thead>
<tr>
<th>Test Item</th>
<th>Test Condition</th>
<th>Failure Size / Sample Size</th>
</tr>
</thead>
<tbody>
<tr>
<td>Soldering Resistance</td>
<td>Reflow peak temperature and moisture soak conditions are specified per package type. 3 times</td>
<td>0 / 32</td>
</tr>
<tr>
<td>Temperature Cycling</td>
<td>-65deg.C (20min) to 25deg.C to 150deg.C (20min) to 25deg.C 500 cycles</td>
<td>0 / 32</td>
</tr>
</tbody>
</table>

## 2. Mechanical tests

<table>
<thead>
<tr>
<th>Test Item</th>
<th>Test Condition</th>
<th>Failure Size / Sample Size</th>
</tr>
</thead>
<tbody>
<tr>
<td>Solderability</td>
<td>Solder temperature : 245deg.C for Solder type Sn-3Ag-0.5Cu Solder immersion time : 5s , Flux type : non-active flux , 1 time</td>
<td>0 / 22</td>
</tr>
<tr>
<td>Lead Integrity (Tension)</td>
<td>Tension : according to relevant specification Maintain the specified tension for 30s</td>
<td>0 / 22</td>
</tr>
</tbody>
</table>

## 3. Life tests

<table>
<thead>
<tr>
<th>Test Item</th>
<th>Test Condition</th>
<th>Failure Size / Sample Size</th>
</tr>
</thead>
<tbody>
<tr>
<td>TBD62083AFG</td>
<td></td>
<td>0 / 32</td>
</tr>
<tr>
<td></td>
<td></td>
<td>0 / 32</td>
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<td></td>
<td></td>
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</tr>
</tbody>
</table>

The information contained in Reliability Test Report represents the result of our internal reliability tests conducted in accordance with JEITA ED-4701 test standards, and is provided for your reference only.

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For detailed reliability test information, such as test conditions and criteria, please contact your Toshiba sales representative.

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Heat-resistant Mounting Conditions

Product Name: FTBD62083AFG
Package Name: FSOP18

1. Reflow
   Peak: 260 deg.C
   Reflow zone: 255 deg.C within 30 seconds, 217 deg.C 60 to 150 seconds
   Preheat: 150 to 200 deg.C, 60 to 120 seconds

   NOTE: All temperatures refer to the package body surface.

   The heat-resistant temperature profile is shown in Fig.1. The temperatures in this profile are the maximum guaranteed temperatures that the device endures. Select the temperatures for a pre-heat and a heat most suitable for your solder paste type, etc., within the conditions described in Fig.1.

2. Others
   We urge you to verify well before mounting to assure enough solder joint strength.

3 times maximum

Always solder the Product in accordance with the heat-resistance mounting conditions set forth above. In the event the Product is soldered otherwise, the applicable product warranty, if any, is void.

Fig.1 Example of Heat-resistant Temperature Profile
Moisture Absorption Control Level (Moisture Sensitivity Level)

Product Name: TBD62083AFG

Package Name: SOP18

Always store the Product under moisture sensitivity level equivalent to level 1 (JEDEC J-STD-020 Moisture Sensitivity Level). In the event the Product is stored otherwise, the applicable warranty, if any, is void.

Always perform reflow soldering in accordance with methods and conditions as specified in applicable engineering documents or specifications provided by Toshiba, or as instructed in writing by your TOSHIBA sales representative.

In the event the Product is soldered otherwise, the applicable product warranty, if any, is void.

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